MA3J142DG, MA3J142EG

Silicon epitaxial planar type

For switching circuits

■ Features

- Two isolated elements contained in one package, allowing high-density mounting

■ Package

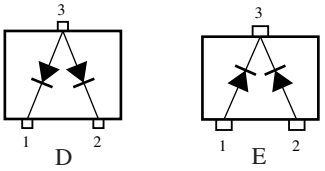
- Code
  SMini3-F2
- Pin Name

MA3J142DG	MA3J142EG
1: Cathode 1	1: Anode 1
2: Cathode 2	2: Anode 2
3: Anode	3: Cathode

■ Marking Symbol

MA3J142DG: MO
MA3J142EG: MU

■ Internal Connection



■ Absolute Maximum Ratings $T_a = 25°C$

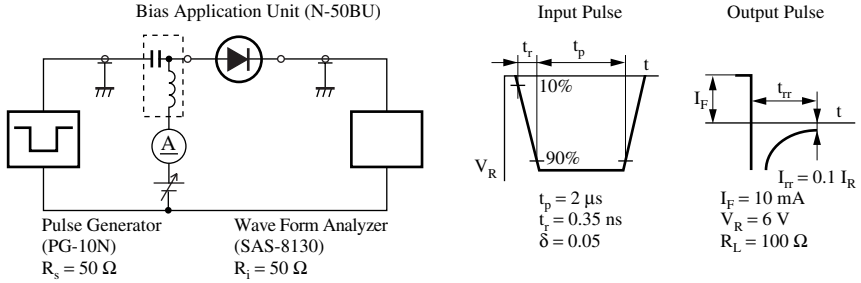
Parameter		Symbol	Rating	Unit
Reverse voltage		V_R	80	V
Maximum peak reverse voltage		V_{RM}	80	V
Forward current	Single	I_F	100	mA
	Double		150	
Peak forward current	Single	I_{FM}	225	mA
	Double		340	
Non-repetitive peak forward surge current *	Single	I_{FSM}	500	mA
	Double		750	
Junction temperature		T_j	150	°C
Storage temperature		T_{stg}	−55 to +150	°C

Note) ∗: t = 1 s

■ Electrical Characteristics $T_a = 25°C \pm 3°C$

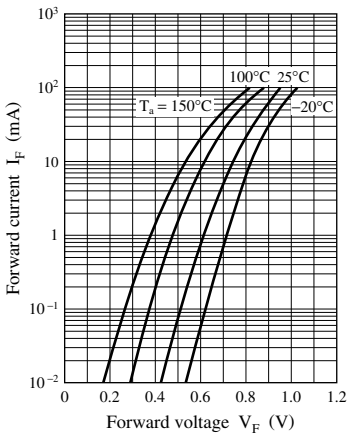
Parameter		Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage		V_F	I_F = 100 mA			1.2	V
Reverse voltage		V_R	I_R = 100 µA	80			V
Reverse current		I_R	V_R = 75 V			100	nA
Terminal capacitance	MA3J142DG	C_t	V_R = 0 V, f = 1 MHz			15	pF
	MA3J142EG					2	
Reverse recovery time *	MA3J142DG	t_{rr}	I_F = 10 mA, V_R = 6 V			10	ns
	MA3J142EG		I_{rr} = 0.1 I_R , R_L = 100 Ω			3	

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. Absolute frequency of input and output is 100 MHz.
3. ∗: t_{rr} measurement circuit

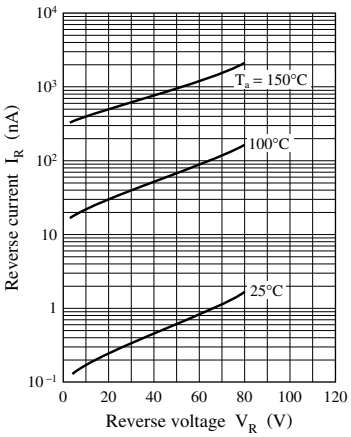


Characteristics charts of MA3J142DG

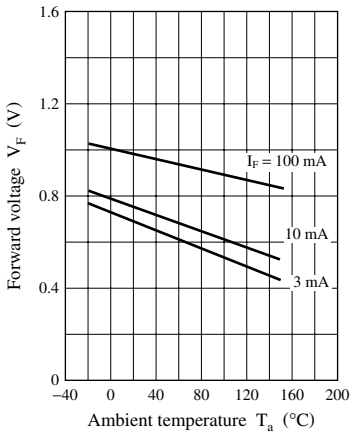
I_F — V_F



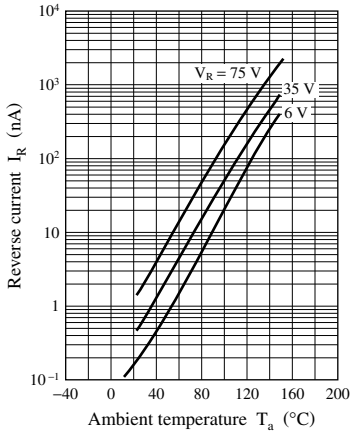
I_R — V_R



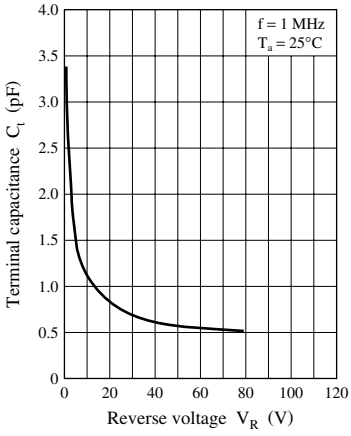
V_F — T_a



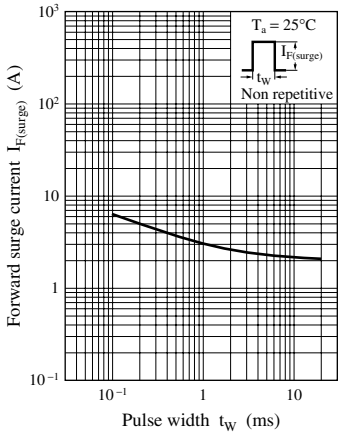
I_R — T_a



C_t — V_R

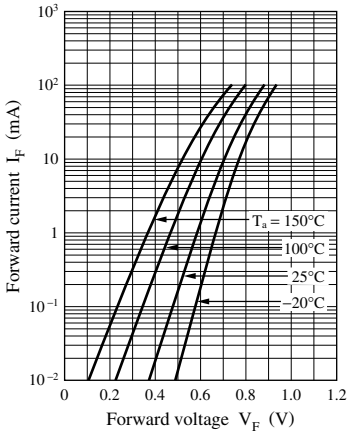


$I_{F(surge)}$ — t_W

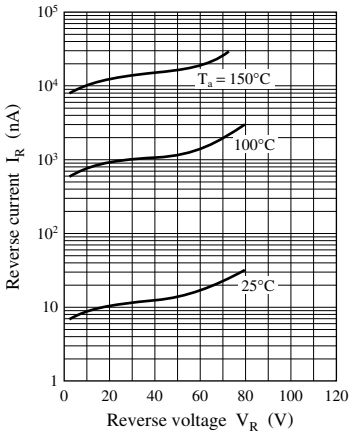


Characteristics charts of MA3J142EG

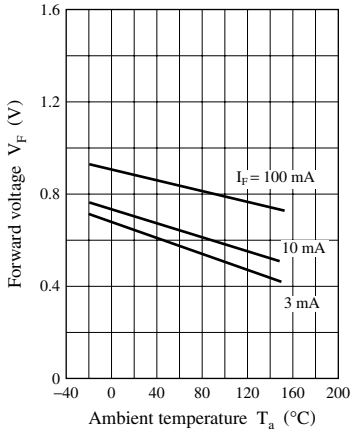
I_F — V_F



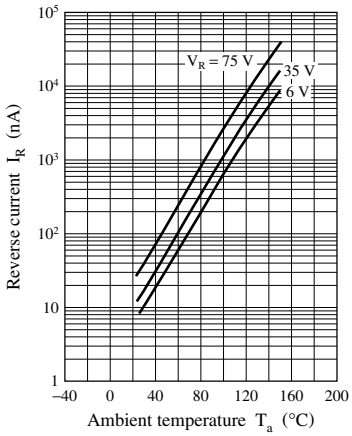
I_R — V_R



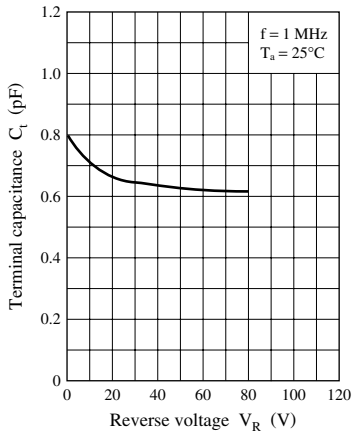
V_F — T_a



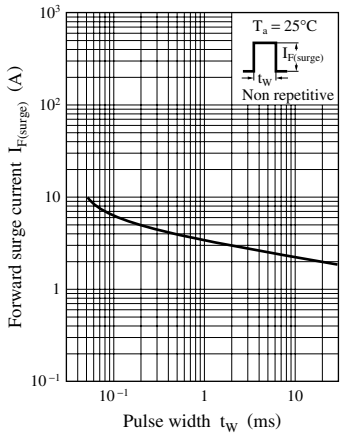
I_R — T_a



C_t — V_R

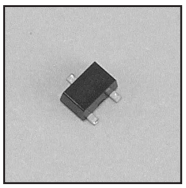


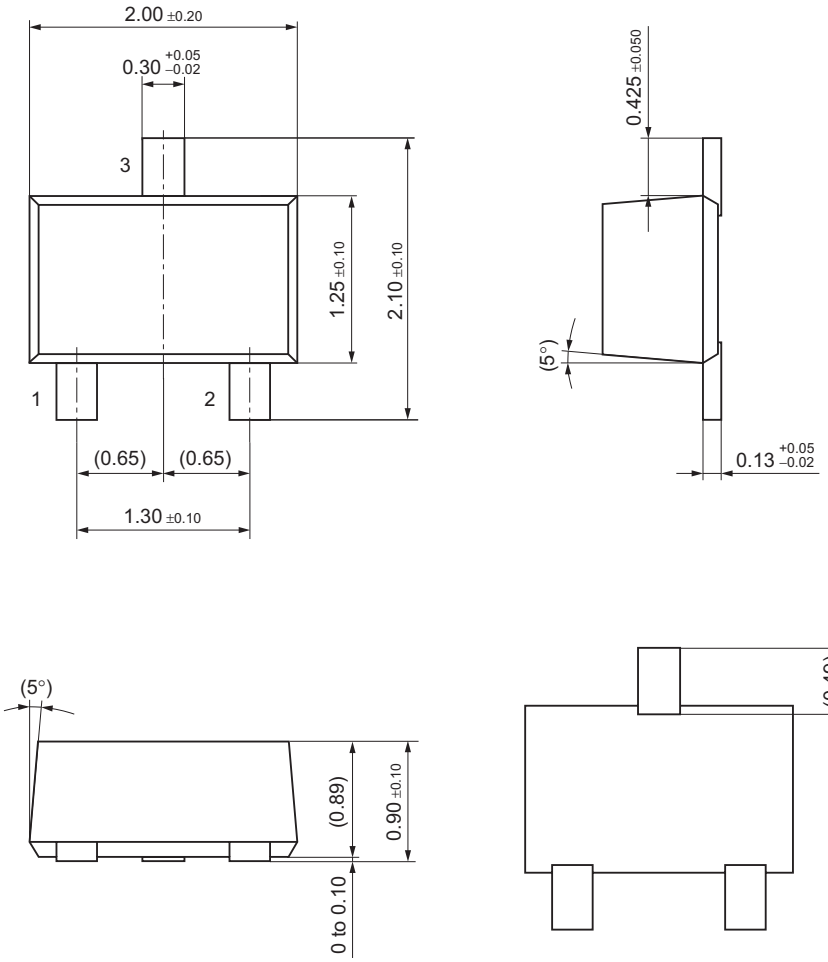
$I_{F(surge)}$ — t_W



SMini3-F2

Unit: mm





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